

Appl. No.: 10/511,792

RECEIVED
CENTRAL FAX CENTER

SEP 06 2007

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Please cancel claim 1-20 and 22 without prejudice.

Listing of Claims:

1-22. (Cancelled)

23. (Previously presented) A method for producing an electronic microcircuit module tape comprising the following steps performed in the following order:

depositing an electrically conductive layer on a first face of a substrate tape, wherein the substrate tape comprises a second opposite face;

gluing a first face of a mask tape on the second opposite face of the substrate tape; and

concurrent with or subsequent to the step of gluing, arranging an adhesive on a second different face of the mask tape;

wherein the mask tape comprises a window open to the second face of the substrate tape, wherein the window is sized and shaped to allow an integrated circuit to be inserted through the window and be subsequently mounted to the second face of the substrate tape after the mask tape has been attached to the substrate tape, and wherein the mask tape has a height greater than a height of an

Appl. No.: 10/511,792

integrated circuit intended to be mounted on the second face of the substrate tape.

24. (Previously presented) A method as in claim 23 further comprising inserting the integrated circuit through the second face of the mask tape through the window and subsequently fixing the integrated circuit against the second face of the substrate tape.

25. (Previously presented) A method as in claim 24 wherein inserting and fixing the integrated circuit occurs after the mask tape is glued to the substrate tape.

26. (Previously presented) A method as in claim 24 wherein the second face of the mask tape comprises a face opposite the first face of the mask tape.

27. (Previously presented) A method as in claim 24 wherein arranging the adhesive on the second different face of the mask tape occurs before the integrated circuit is fixed to the substrate tape.

28. (Previously presented) A method as in claim 24 wherein arranging the adhesive on the second different face of the mask tape occurs after the integrated circuit is fixed to the substrate tape.